

Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 1 May 2009 [Approved on 10 March 2016, 16:33 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.5%	Nickel	7440-02-0	1%
			Gold	7440-57-5	11.5%
			Dow corning 3110	63394-02-5	25%
			Silicon	7440-21-3	62.5%
Die attach	Sn-Pb solder	0.03%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	43%	Carbon black	1333-86-4	0.3%
			Epoxy resin 89	26335-32-0	28.3%
			Quartz sand	60676-86-0	71.4%
Leadfinish	Tin plating	0.5%	Silver	7440-22-4	3.5%
			Tin	7440-31-5	96.5%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	55.97%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
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Part number	Part name	Part Mass	Part Mass UoM
PowerQFN 5x6	Diode/Transistor Power	0.1	g

No need to provide safe use information beyond the identification of the Candidate List substance